Market Data

MARKET INTELLIGENCE TEAM

GLOBAL SEMICONDUCTOR PACKAGING MATERIALS OUTLOOK

2024 EDITION

This 2024 edition of the *Global Semiconductor Packaging Materials Outlook (GSPMO)* is authored by TECHCET and TechSearch International, Inc., in cooperation with SEMI. The report covers the packaging materials markets, including substrates, lead frames, bonding wire, encapsulation materials, underfill materials, die-attach, solder balls, wafer-level package dielectrics, and wafer-level plating chemicals.

Global Semiconductor Packaging Materials Outlook is an essential business tool for anyone interested in the plastic packaging materials arena. Packaging materials directly affect the performance, reliability and cost of semiconductors, and advancements in packaging materials technology offer the potential for significant improvement across all these areas.

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FEATURES

- Technology trends
- Regional market size and forecast
- Five-year market forecasts
- Supplier information and market share
- Market size by product segments in revenue and units

BENEFITS

- Gain insights to worldwide packaging material technology trends, market size, and market forecast
- Understand key package offerings and technologies
- Use benchmark data to validate business opportunities and assumptions

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METHODOLOGY

The source of information for this study are in-person interviews with over 150 material suppliers, packaging subcontractors, and semiconductor manufacturers from around the world. The authors of this report used primary research and modeling to develop market size information, and developed five-year market forecasts based on different scenarios of new technology penetration and market growth.

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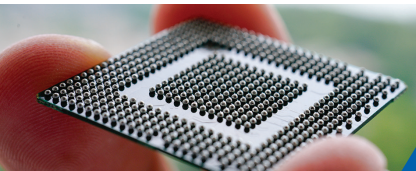

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